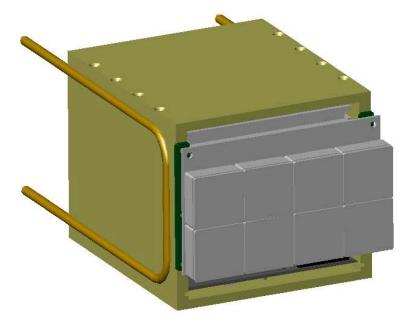
TOP Electro-mechanical Update (Fuji Hall/back-end update separate)



4-MAR-2013

M. Andrew, K. Le, G. Jung, B. Kirby, L. Macchiarulo, B. Macek, M. Rosen, X. Shi, G. Varner, C. Yee

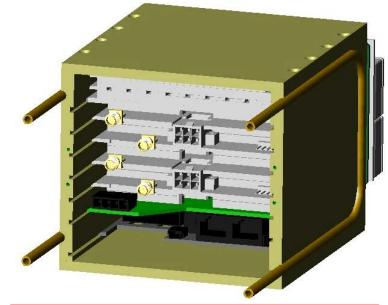
Improved packaging/thermal



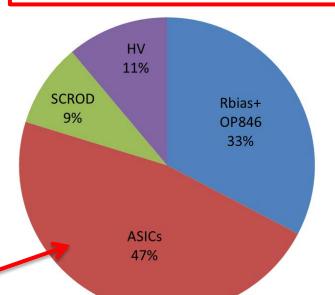
Full TOP, measured numbers

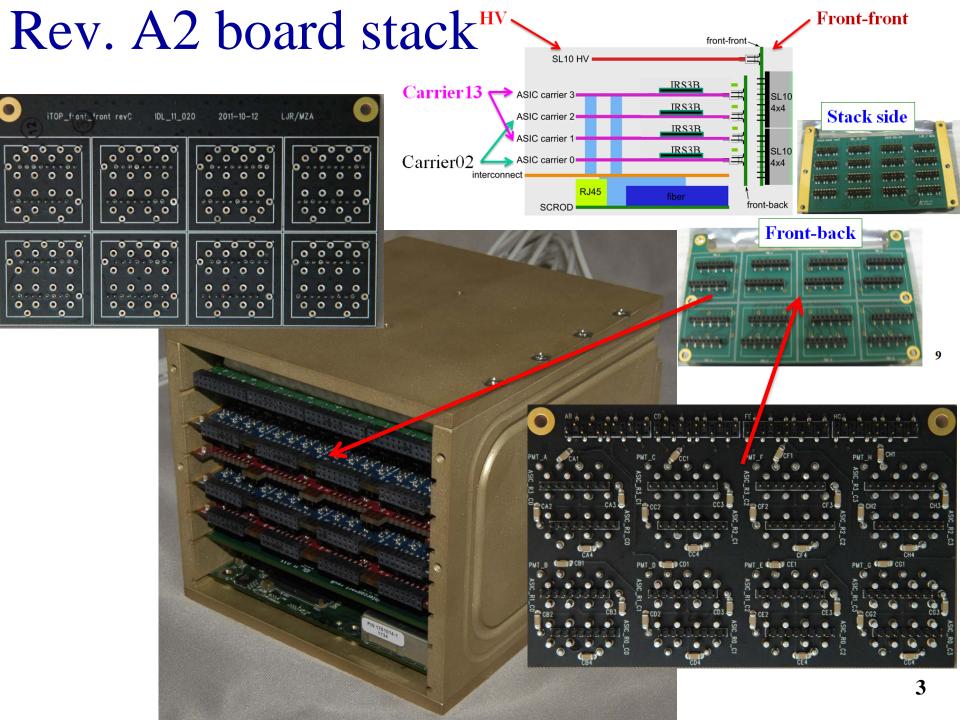
Rbias+OP846	40 W
ASICs	57.6W
SCRODs	11.2W
HV	13.6W
Total	122.4W

May be possible to tune biases lower



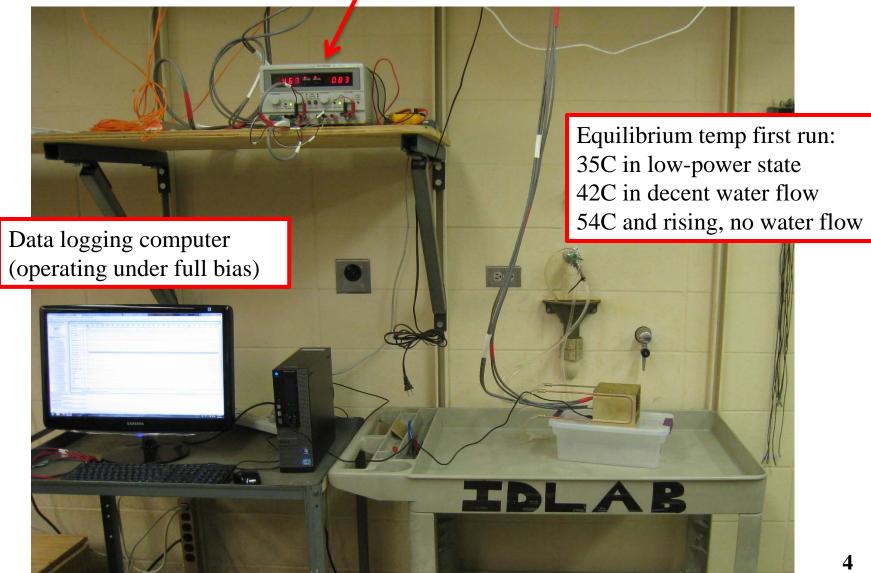
About 31W per board-stack module





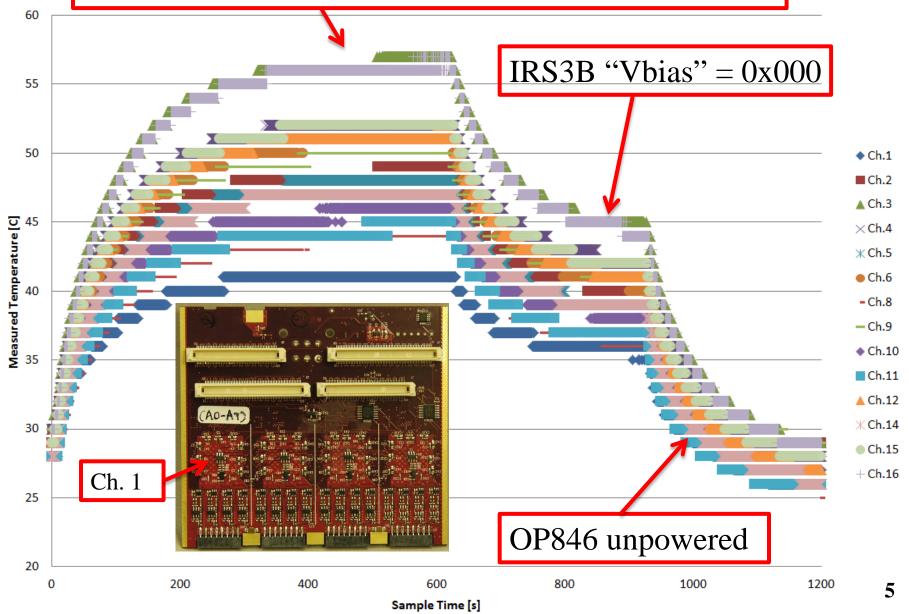
Thermal test bench – Run 1

Module Power: 4.6A @ 3V, 0.8A @ 4V, 2A @ 5V

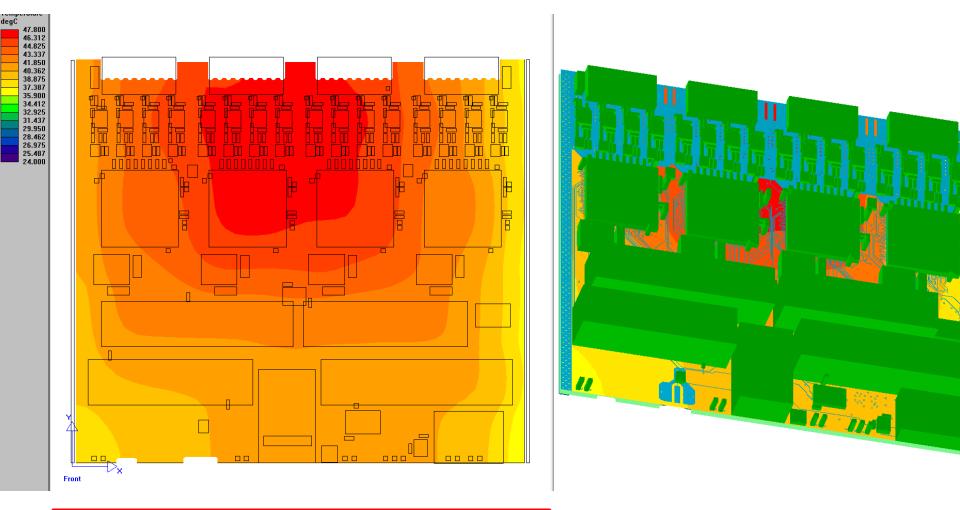


Summary of Run 4

Nominal Biases: 4.6A @ 3V, 0.86A @ 4V, 2A @ 5V



Revised Thermal Model



Clearly need to do a better job of coupling To sidewalls (with water flow cool to touch) Consider compression/ Wedge lock mechanism

Initial Testing

• 62 of 64 IRS3B ASICs verified, all channel 1 see calibration input signal (1 AMUX problem? other is likely configuration debug). Packaged up in thermal housings and 512 channels of readout being delivered to Fuji Hall

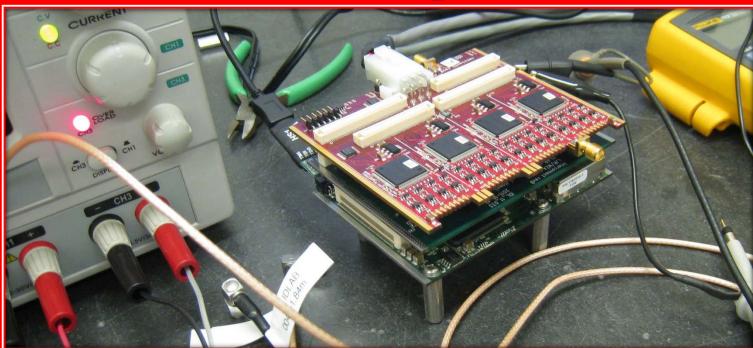
• Having programmable control over fine timing adjusts permits automated scans of parameters

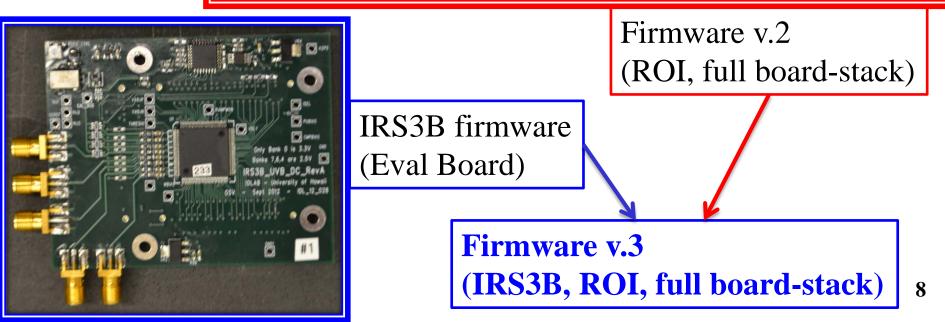
• A few minor issues with I^2C addressing and external DAC bypassing – all have straightforward, though firmware-tedious work-arounds Carrier 02 (top)

Interconnect Rev. A (mid)

SCROD A2 (bottom)

Firmware Development Status

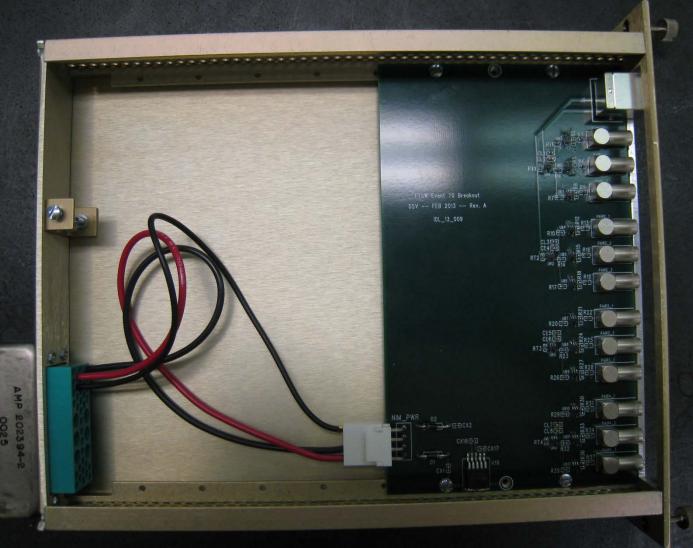




Fuji Hall Integration

- Integrated power supplies not ready; short term solution (should be ready for CRT(?) or LEPS)
- Next 2 weeks critical for commissioning and debugging data flow FTSW timing verification crucial (new FTSW LVDS NIM module)
- Interconnect board Rev. C delayed (has built-in cal source features for now use ext sig gen); new chassis still to be machined (slide 11)
- Can do voltage, timing, alignment scans "on demand" on all 512 readout channels in situ

FTSW Aux Monitor (Event T0)

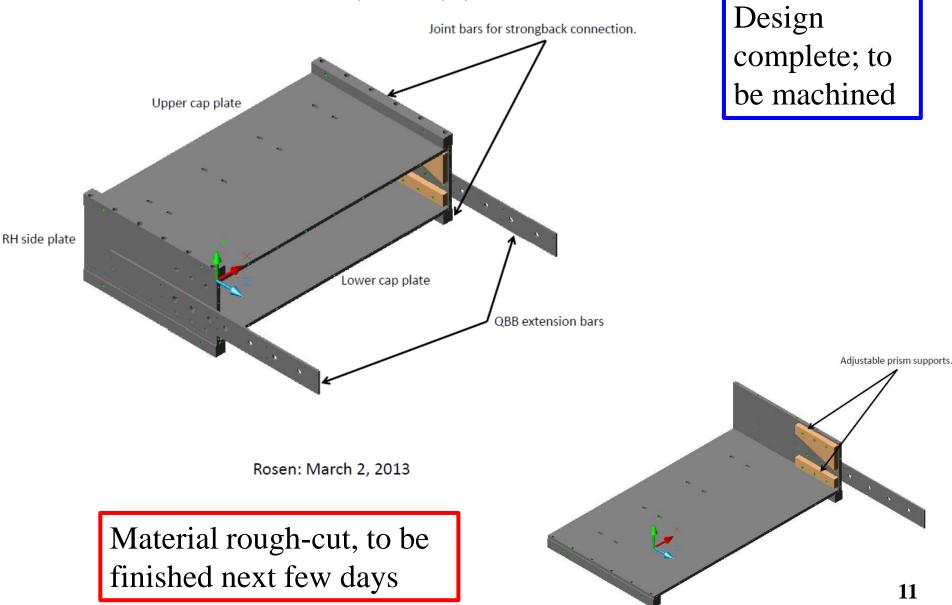


Each AUX LVDS monitor pair has 3x NIM output copies

Tested with FTSW – outer channels Work (network cross-over cable)

New Readout Chassis

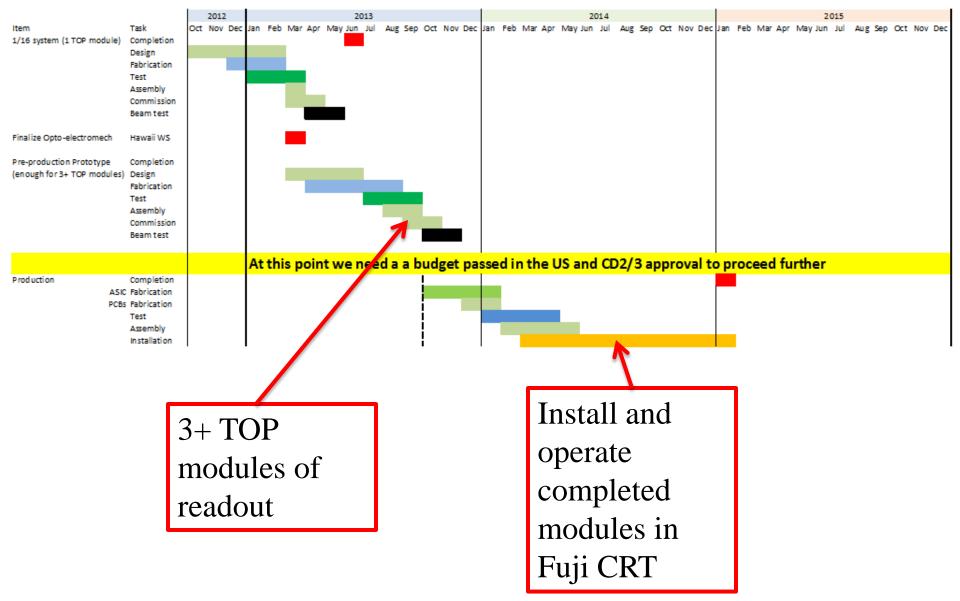
Readout chassis with all components displayed.



Electro-mechanical Summary

- IRS3B working very well (only change being considered is a method to reduce power-on current surge). No major problems Rev A2 boards
- Full TOP bar "1/16 prototype" E-M readout delivered for installation in Fuji Hall this week; integration with COPPER-based readout
- Firmware works in pieces needs to be integrated, debugged and commissioned (March)
- On schedule for April Cosmic Campaign and pre-qualified May LEPS beam test

Schedule



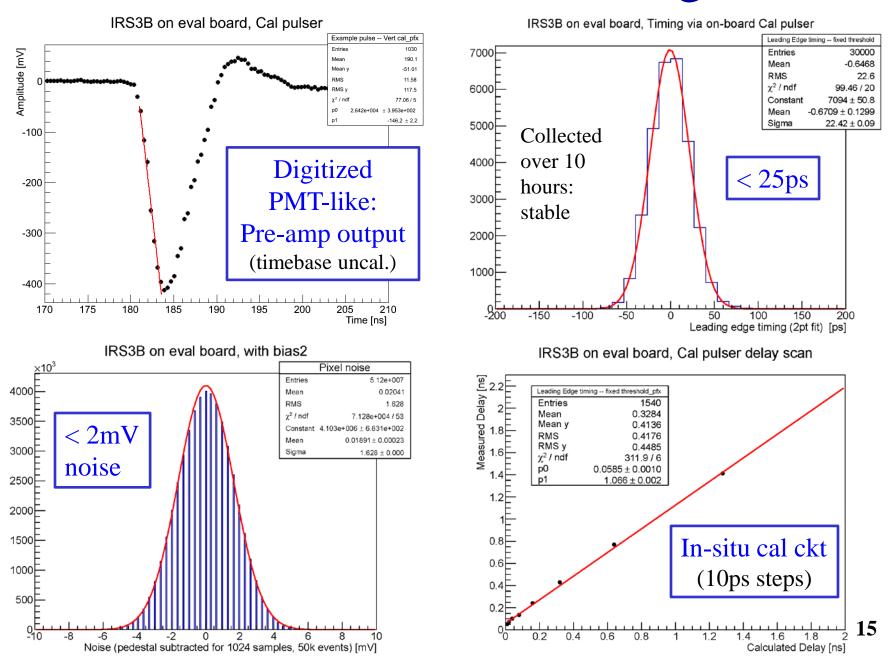
Items Prior to Production

- ✓ 1. ASIC configuration, sampling issues
- 2. Timebase stabilization (servo-loop)
 - 1. Firmware needed to be re-written
 - 2. Improved phase control
- 3. SCROD module ("final" form factor)
 - 4. Better thermal management (85C redline ops)
 - 5. HV divider redesign
 - 6. Improved SL-10 electro-mech interface
 - 7. Demonstrate DSP (real time) data reduction
 - 8. In-situ (on demand) calibration

= Demonstrated



IRS3B and Readout working well



Performance Requirements (TOP) • Single photon timing for MCP-PMTs

